

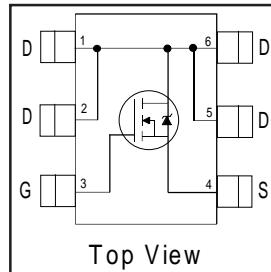
International **IR** Rectifier

PD- 93758B

IRLMS2002

HEXFET® Power MOSFET

- Ultra Low On-Resistance
- N-Channel MOSFET
- Surface Mount
- Available in Tape & Reel
- 2.5V Rated

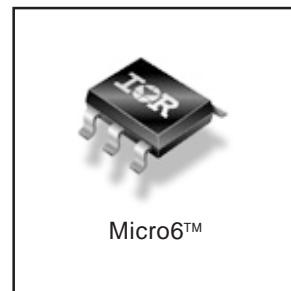


$V_{DSS} = 20V$
 $R_{DS(on)} = 0.030\Omega$

Description

These N-Channel MOSFETs from International Rectifier utilize advanced processing techniques to achieve the extremely low on-resistance per silicon area. This benefit provides the designer with an extremely efficient device for use in battery and load management applications.

The Micro6™ package with its customized leadframe produces a HEXFET® power MOSFET with $R_{DS(on)}$ 60% less than a similar size SOT-23. This package is ideal for applications where printed circuit board space is at a premium. Its unique thermal design and $R_{DS(on)}$ reduction enables a current-handling increase of nearly 300% compared to the SOT-23.



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain- Source Voltage	20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	6.5	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	5.2	
I_{DM}	Pulsed Drain Current ①	20	
$P_D @ T_A = 25^\circ C$	Power Dissipation	2.0	W
$P_D @ T_A = 70^\circ C$	Power Dissipation	1.3	
	Linear Derating Factor	0.016	W/°C
V_{GS}	Gate-to-Source Voltage	± 12	V
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

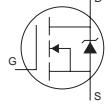
Thermal Resistance

	Parameter	Max.	Units
$R_{θJA}$	Maximum Junction-to-Ambient ③	62.5	°C/W

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	20	—	—	V	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}/\Delta T_J}$	Breakdown Voltage Temp. Coefficient	—	0.016	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1\text{mA}$
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	0.030	Ω	$V_{\text{GS}} = 4.5\text{V}$, $I_D = 6.5\text{A}$ ②
		—	—	0.045		$V_{\text{GS}} = 2.5\text{V}$, $I_D = 5.2\text{A}$ ②
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	0.60	—	1.0	V	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$
g_{fs}	Forward Transconductance	13	—	—	S	$V_{\text{DS}} = 10\text{V}$, $I_D = 6.5\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	μA	$V_{\text{DS}} = 16\text{V}$, $V_{\text{GS}} = 0\text{V}$
		—	—	25		$V_{\text{DS}} = 16\text{V}$, $V_{\text{GS}} = 0\text{V}$, $T_J = 70^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{\text{GS}} = -12\text{V}$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{\text{GS}} = 12\text{V}$
Q_g	Total Gate Charge	—	15	22	nC	$I_D = 6.5\text{A}$
Q_{gs}	Gate-to-Source Charge	—	2.2	3.3		$V_{\text{DS}} = 10\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	3.5	5.3		$V_{\text{GS}} = 5.0\text{V}$ ②
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	8.5	—	ns	$V_{\text{DD}} = 10\text{V}$
t_r	Rise Time	—	11	—		$I_D = 1.0\text{A}$
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	36	—		$R_G = 6.0\Omega$
t_f	Fall Time	—	16	—		$R_D = 10\Omega$ ②
C_{iss}	Input Capacitance	—	1310	—	pF	$V_{\text{GS}} = 0\text{V}$
C_{oss}	Output Capacitance	—	150	—		$V_{\text{DS}} = 15\text{V}$
C_{rss}	Reverse Transfer Capacitance	—	36	—		$f = 1.0\text{MHz}$

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	2.0	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	20		
V_{SD}	Diode Forward Voltage	—	—	1.2	V	$T_J = 25^\circ\text{C}$, $I_S = 1.7\text{A}$, $V_{\text{GS}} = 0\text{V}$ ②
t_{rr}	Reverse Recovery Time	—	19	29	ns	$T_J = 25^\circ\text{C}$, $I_F = 1.7\text{A}$
Q_{rr}	Reverse Recovery Charge	—	13	20	nC	$dI/dt = 100\text{A}/\mu\text{s}$ ②

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

③ Surface mounted on FR-4 board, $t \leq 5\text{sec}$.

② Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

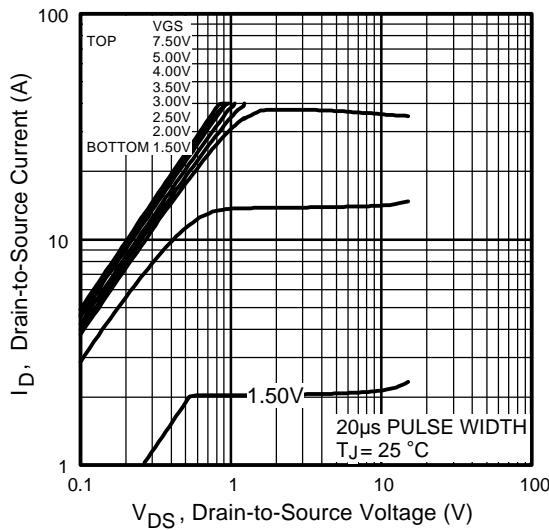


Fig 1. Typical Output Characteristics

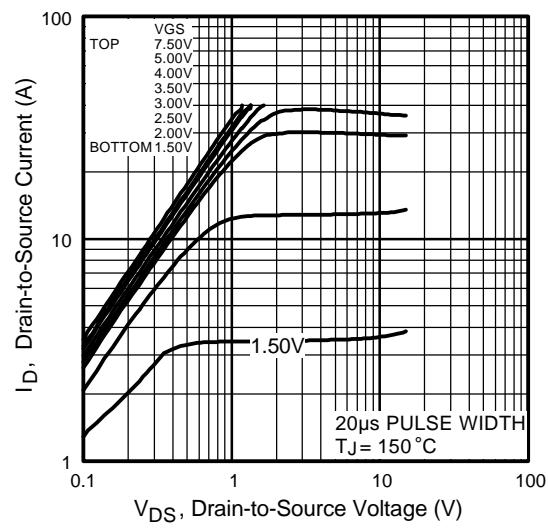


Fig 2. Typical Output Characteristics

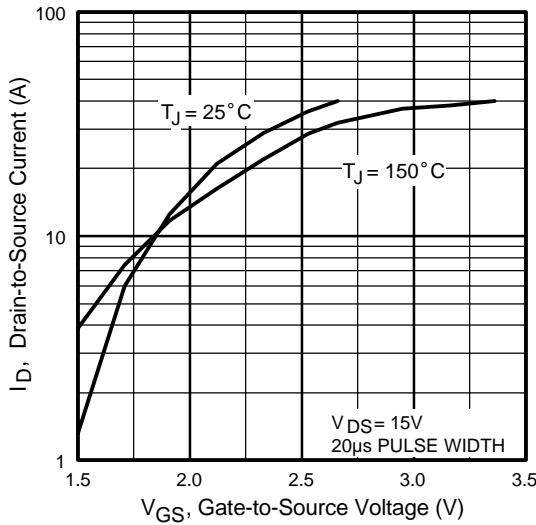


Fig 3. Typical Transfer Characteristics

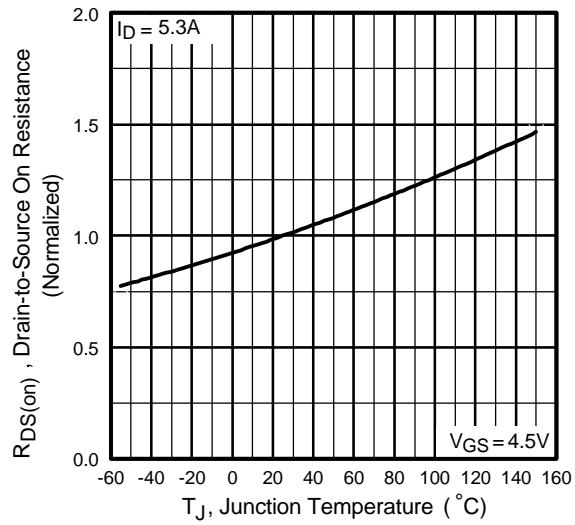


Fig 4. Normalized On-Resistance
Vs. Temperature

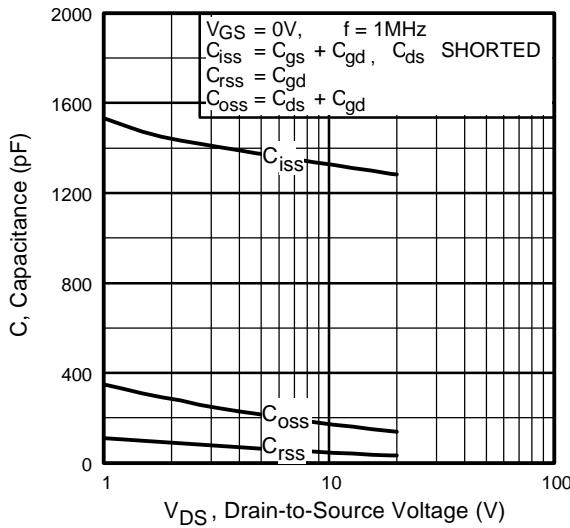


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

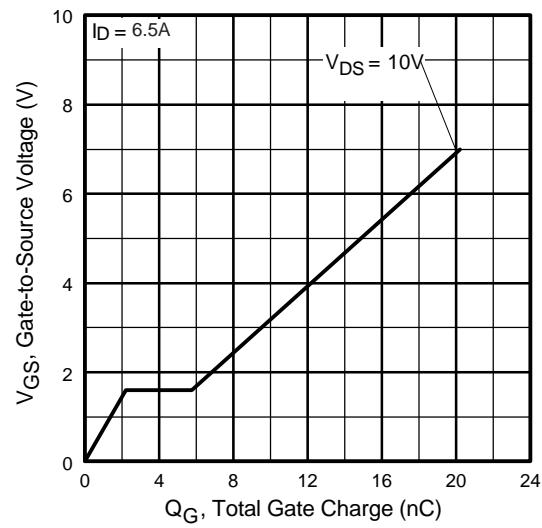


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

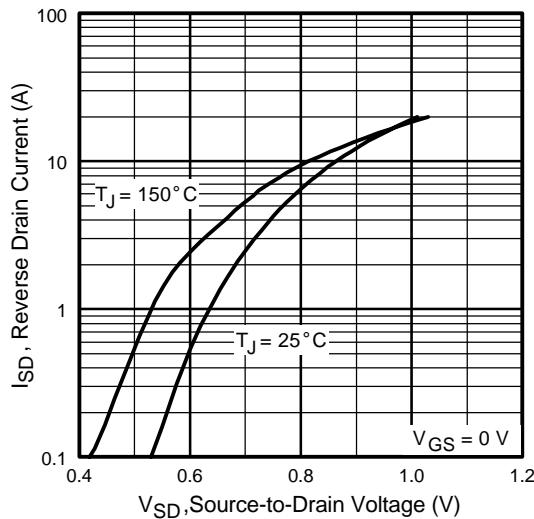


Fig 7. Typical Source-Drain Diode
Forward Voltage

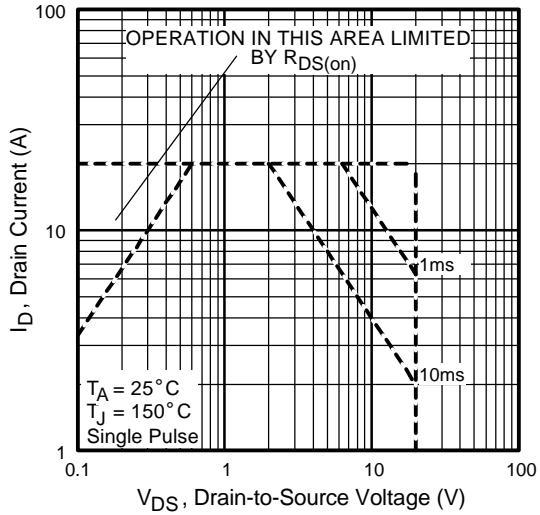


Fig 8. Maximum Safe Operating Area

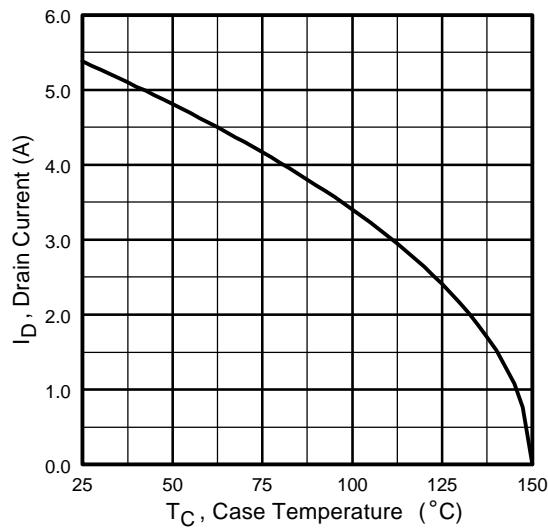


Fig 9. Maximum Drain Current Vs.
Case Temperature

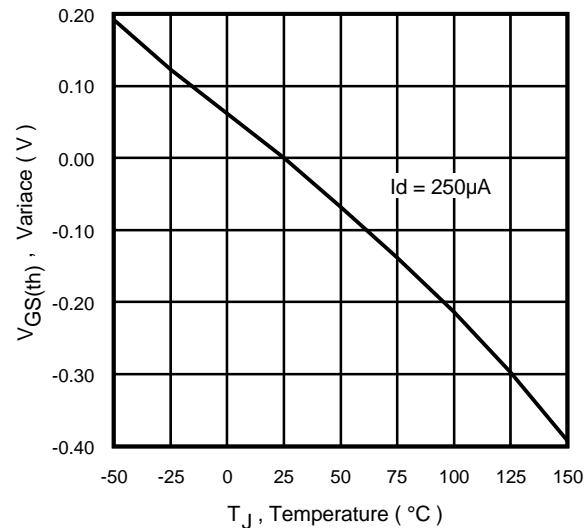


Fig 10. Typical $V_{GS(th)}$ Variance Vs.
Junction Temperature

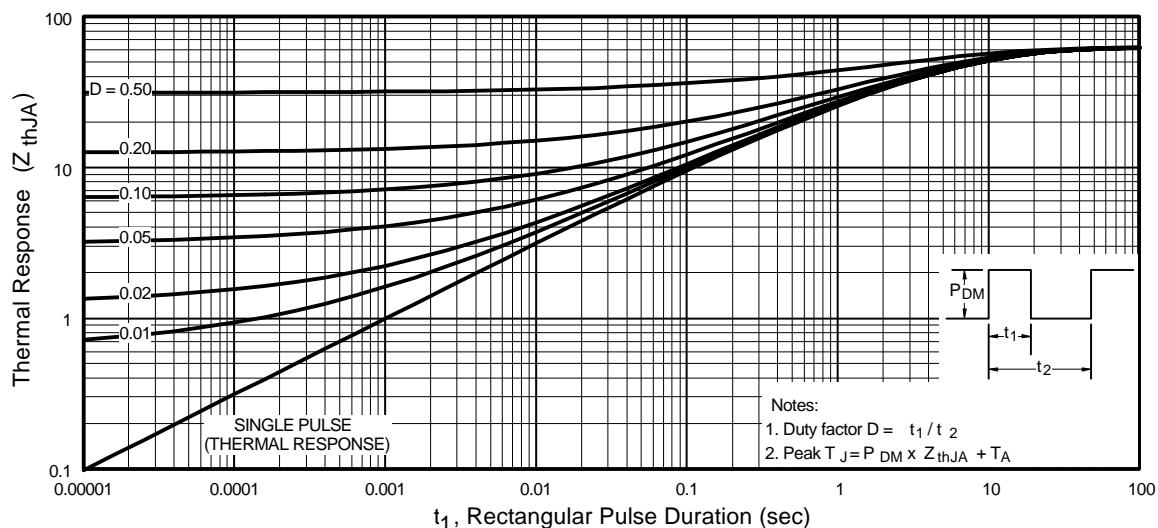


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

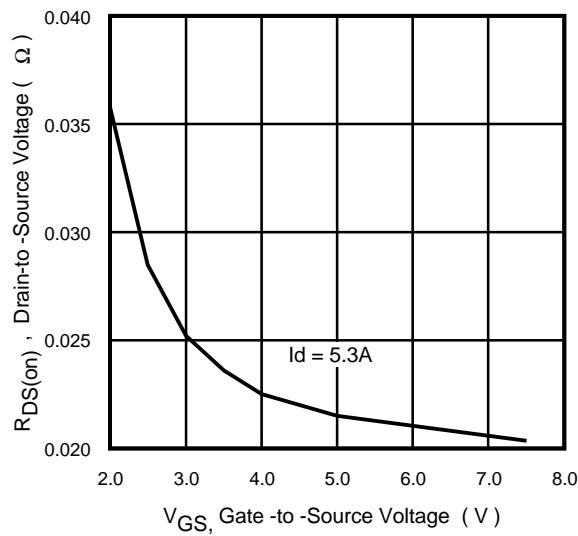


Fig 12. Typical On-Resistance Vs.
Gate Voltage

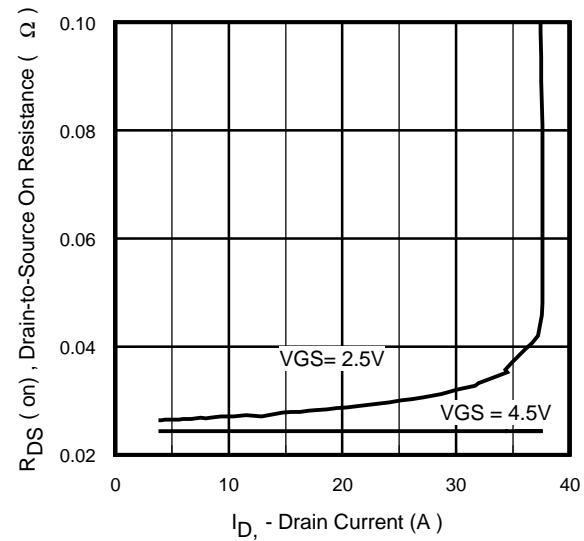
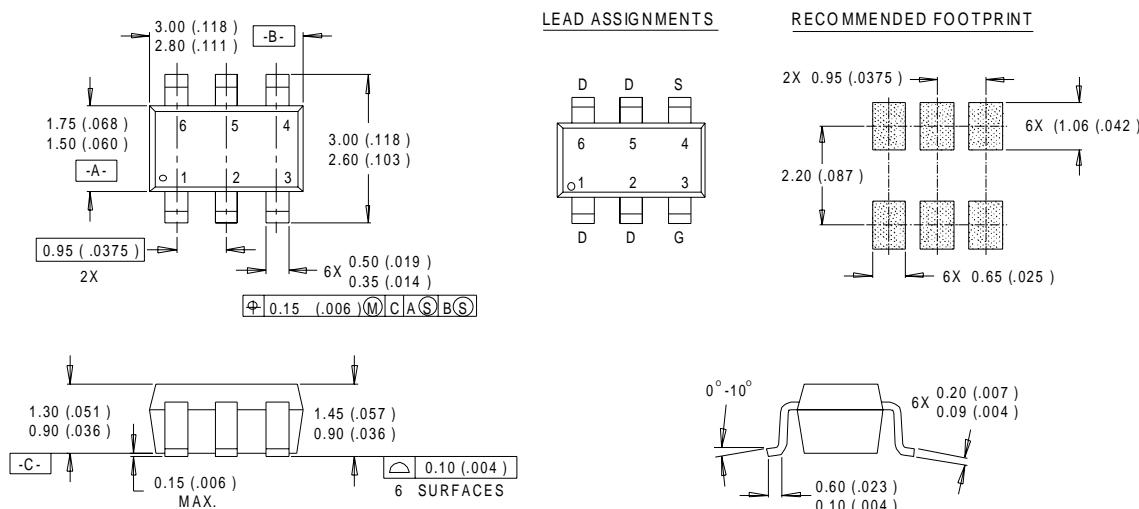


Fig 13. Typical On-Resistance Vs.
Drain Current

Micro6™ Package Outline



NOTES :

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

Micro6™ Part Marking Information

EXAMPLE : THIS IS AN IRLMS6702

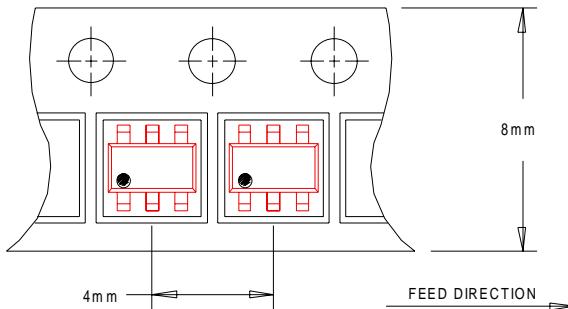
PART NUMBER	DATE CODE	YEAR	Y	WORK WEEK	W	YEAR	Y	WORK WEEK	W
	2C YW	2001	1	01	A	2001	A	27	A
	2C YW	2002	2	02	B	2002	B	28	B
	2C YW	2003	3	03	C	2003	C	29	C
	2C YW	2004	4	04	D	2004	D	30	D
	XXXX	2005	5			2005	E		
		1996	6			1996	F		
		1997	7			1997	G		
		1998	8			1998	H		
		1999	9			1999	J		
		2000	0	24	X	2000	K	50	X
								51	Y
								52	Z

PART NUMBER EXAMPLES: 2A = IRLMS1902 2B = IRLMS1503 2C = IRLMS6702 2D = IRLMS5703

DATE CODE EXAMPLES: YWW = 9603 = 6C YWW = 9632 = FF

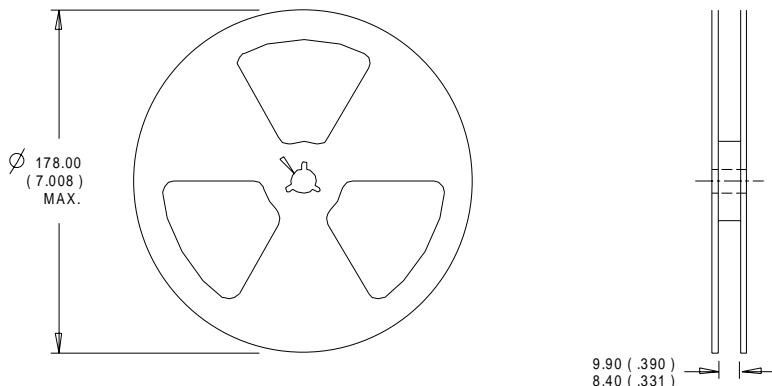
WORK WEEK = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR
WORK WEEK = (27-52) IF PRECEDED BY A LETTER

Micro6™ Tape & Reel Information



NOTES :

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

International
IR Rectifier

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